

To: Business Editor
(Immediate Release)



Hua Hong Semiconductor Limited 華虹半導體有限公司

Hua Hong Semiconductor's 90nm G2 eFlash Process Platform Successfully Achieved Mass Production

(27 December, 2017, Hong Kong) **Hua Hong Semiconductor Limited** (“**Hua Hong Semiconductor**” or the “**Company**”, together with its subsidiaries, the “**Group**”; stock code: 1347.HK), a global leading pure-play 200mm foundry, today announced the successful mass production of its second-generation 90nm eFlash (90nm G2 eFlash) process platform, which has further enhanced the Company’s technical capabilities and competitiveness.

Based on the first-generation 90nm eFlash (90nm G1 eFlash) process technology, Hua Hong Semiconductor realized technological advancement of its 90nm G2 eFlash process platform in multiple aspects. 90nm G2 has a shrunk Flash cell size, which is about 25% smaller than that of the first-generation – the smallest around the globe among all foundries’ 90nm process node eFlash technology. In addition, the new Flash IP architecture adopted in 90nm G2 ensures high reliability (100,000 write/erase cycles and data retention for 25 years) while having a Flash IP with low power consumption and extremely compact area. This significantly reduces the overall chip size of the 90nm G2 eFlash, so that single wafers can accommodate more dies. This advantage of the 90nm G2 eFlash is particularly significant for chips with higher eFlash density. It is also worth noting that based on the foundations laid down in the first-generation, the 90nm G2 eFlash further reduced one more layer of masks, which has pushed the manufacturing cost down to an even lower level.

Now in mass production with high and stable yield, the 90nm G2 eFlash has already been applied on large-scale production of SIM card ICs, and it will provide manufacturing solutions that are more cost-effective for the ICs of diversified products, such as smart cards, security chips, and micro-controller units (MCUs).

“The successful mass production of 90nm G2 eFlash marks another success for Hua Hong Semiconductor in the area of specialty technology of embedded Flash,” said **Dr. Kong Weiran, Executive Vice President of Hua Hong Semiconductor**. “Embedded NVM (Non-Volatile Memory) technology, as one of our strategic focuses, has always been well-recognized by the industry for its high security, reliability, cost-effectiveness and technical sophistication. As the leading foundry for smart card ICs, Hua Hong Semiconductor will stay on course to optimize its technologies and upgrade its platforms to maintain its leadership in the area of smart card ICs, and tap potentials in high-growth emerging markets such as IoT (Internet of Things) and new energy vehicles.”

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About Hua Hong Semiconductor Limited

Hua Hong Semiconductor (Stock Code: 1347.HK) is a global leading pure-play 200mm foundry, primarily focusing on research and manufacturing of semiconductors on 200mm wafers for specialty applications, in particular eNVM and power discretes. The Group's portfolio also includes several other advanced process technologies such as RFCMOS, analog and mixed signal, PMIC and MEMS. According to IHS, based on total 2016 revenues, the Group ranked second globally amongst pure-play 200mm foundries. The semiconductors Hua Hong Semiconductor manufactures are incorporated into a wide range of products in diverse markets, including consumer electronics, communications, computing, industrial and automotive. Hua Hong Semiconductor uses its own proprietary processes and techniques to manufacture semiconductors of the design specifications for its diverse customers. The Group currently has one of the largest 200mm wafer processing capacities in China through its three fabs in Shanghai, with an approximate total capacity of 166,000 wafers per month as of September 30, 2017. The Group also offers design enablement services facilitating the timely completion of complex designs that are optimized in terms of performance, cost and manufacturing yield on its processes.

Hua Hong Semiconductor's current business is mainly operated and developed through Shanghai Huahong Grace Semiconductor Manufacturing Corporation ("HHGrace"), which is its subsidiary based in Shanghai. HHGrace was incorporated through the consolidation between Shanghai Hua Hong NEC Electronics Company, Limited and Grace Semiconductor Manufacturing Corporation.

For more information please visit: www.huahonggrace.com

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